

In the Claims

Please amend the claims as follows:

1(currently amended). A multilayered substrate for a semiconductor device, comprising:
a multilayered substrate body formed of a plurality of conductor layers and insulation layers, and having a face for mounting a semiconductor element thereon and another face for external connection terminals, the face for mounting a semiconductor element comprising pads through which the substrate is connected to the semiconductor element to be mounted thereon, and the face for external connection terminals comprising pads through which the substrate is connected to an external electrical circuit, wherein a reinforcing sheet is ~~respectively~~ joined to each of the face for mounting a semiconductor element thereon and the face for external connection terminals of the multilayered substrate body, and wherein the pads provided at the face for mounting a semiconductor element thereon are in the form of a bump so that the tip of the pad protrudes from the face for mounting a semiconductor element of the multilayered substrate body.

2-11 (Cancelled).

12.(previously presented) The multilayered substrate for a semiconductor device of claim 1, wherein the reinforcing sheet joined to the face for mounting a semiconductor element thereon is in the form of a frame made of a metal, and the frame is formed by etching a metal sheet on which the multilayered substrate body is formed so as to remove only the metal material in the region where a semiconductor element is to be mounted.

13 (Cancelled).

14.(previously presented) The multilayered substrate for a semiconductor device of claim 1, wherein the reinforcing sheet joined to the face for external connection terminals has through holes corresponding to the respective pads for the external connection terminals, and the pads provided at the face for mounting a semiconductor element thereon are in the form of bump so that the tip of the pad protrudes from the face for mounting a semiconductor element of the multilayered substrate body.

15.(currently amended) The multilayered substrate for a semiconductor device of claim 1 wherein the reinforcing sheet joined to the face for external connection terminals is in the form of frame, and wherein the pads provided at the face for mounting a semiconductor element thereon are in the form of a bump so that the tip of the pad protrudes from the face for mounting a semiconductor element of the multilayered substrate body.

16-21 (Cancelled)

22. (previously presented). The multilayered substrate for a semiconductor device of claim 1, wherein the reinforcing sheet joined to the face for mounting a semiconductor element thereon is in the form of a frame made of a metal, and the frame is formed by etching a metal sheet on which the multilayered substrate body is formed so as to remove the metal material in the region where a semiconductor element is to be mounted.

23. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet comprises aluminum.

24. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet comprises copper.

25. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet comprises a nickel film.

26. (Previously presented). The multilayered substrate for a semiconductor device of claim 22, wherein the reinforcing sheet metal is treated to provide electrical insulation thereon.